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T-688 P.001/034 F-684 ONS00181 PATENT

## IN THE UNITED STATES-PATENT AND TRADEMARK OFFICE

In re application of:

: Date: November 19, 2003

Peyman Hadizad et al.

Serial No.: 09/802,726

: Group Art Unit: 2813

Filed: March 12, 2001

: Examiner: Laura M.

Schillinger

For: SEMICONDUCTOR COMPONENT AND METHOD OF MANUFACTURING

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING FACSIMILE TRANSMITTED TO THE PATENT AND TRADEMARK OFFICE, ATTENTION EXAMINER Laura M. Schillinger, AT THE FAX NUMBER (703) 872-Date of Facsimile Transmission No. of Pages:

Lysia McNamara Name of Person Signing Certificate maranaca

PETITION UNDER 37 CFR 1.97(d), CERTIFICATION UNDER 37 CFR 1.97(e), AND DISCLOSURE STATEMENT UNDER 37 CFR 1.56

HONORABLE ASSISTANT COMMISSIONER FOR PATENTS, Alexandria, VA 22313-1450

Sir:

Applicants herewith petition the Commissioner of Patents to consider this information disclosure statement.

Please charge Deposit Account No. 501086 in the amount of \$180.00 in accordance with 37 CFR 1.17(p). Any deficiency or overpayment should be charged or credited to the above stated Deposit Account.

Applicants respectfully request that the Examiner consider the art listed below in the examination of the subject application and that it be made of record therein. Applicants have enclosed copies of the below listed documents. No warranty is made or implied that an exhaustive search has been conducted or that no other or no more relevant art exists.

I hereby certify that to my knowledge, after reasonable inquiry, no item contained in this information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of this information disclosure statement.

- 1. U.S. Patent No. 6,608,350 B2 issued to Kinzer et al. on August 19, 2003, which discloses a vertical conduction superjunction semiconductor device.
- 2. U.S. Patent No. 6,509,240 B2 issued to Ren et al. on January 21, 2003, which discloses a method of forming a portion of a superjunction semiconductor device.
- 3. U.S. Patent No. 6,410,958 Bl issued to Usui et al. on June 25, 2002, which discloses a vertical superjunction semiconductor device.

Respectfully submitted,

Peyman Hadizad et al.

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